Semiconductor Device Type: JQC 064 LFBGA 9x9x1.72mm SAC305				Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials: 8.1 Electronics (e.g. pc boards, displays)			
	<u>,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,</u>	"Contained In"	% Total			175.69	(mg) Total	Mold Compound	% ot Total Weight	56.04
Basic Substance Silica(Amorphous) A	60676-86-0	Sub-Component Mold Compound	Weight 42,198	mg/part 132.291	ppm 421.981		Silica(Amorphous) A	60676-86-0	75.30	
Silica(Amorphous) A Silica(Amorphous) B	7631-86-9	Mold Compound	5.626	17.639	56,264		Silica(Amorphous) A Silica(Amorphous) B	7631-86-9	10.04	
Epoxy Resin	Trade Secret	Mold Compound	4.534	14.213	45,336		Epoxy Resin	Trade Secret	8.09	
Phenol Resin	9003-35-4	Mold Compound	1.687	5.288	16,868		Phenol Resin	9003-35-4	3.01	
Aluminium and its compounds	1332-58-7	Mold Compound	1.687	5.288	16,868	Alu	minium and its compounds	1332-58-7	3.01	
Carbon Black	1333-86-4	Mold Compound	0.308	0.966	3,082		Carbon Black	1333-86-4	0.55	
Copper	7440-50-8	Lead Frame	10.993	34.462	109,926			Total	100.00	
Glass fibers	65997-17-3	Lead Frame	6.553	20.543	65,527	95.99	(mg) Total	Lead Frame	% of Total Weight	30.62
Phenol, polymer	9003-36-5	Lead Frame	6.553	20.543	65,527		Copper	7440-50-8	35.90	
Silica, chemically prepared	7631-86-9	Lead Frame	2.450	7.679	24,496		Glass fibers	65997-17-3	21.40	
Nickel	7440-02-0	Lead Frame	1.194	3.744	11,942		Phenol, polymer	9003-36-5	21.40	
Barite	7727-43-7	Lead Frame	0.766	2.400	7,655		Silica, chemically prepared Nickel	7631-86-9	8.00	
Magnesium silicate Araldite GY 250	14807-96-6 25068-38-6	Lead Frame Lead Frame	0.612	1.920 1.920	6,124 6,124		Nickel Barite	7440-02-0 7727-43-7	3.90 2.50	
(2-Methoxymethylethoxy)propanol	34590-94-8	Lead Frame	0.612	0.768	2,450		Magnesium silicate	14807-96-6	2.50	
Bisphenol A	80-05-7	Lead Frame	0.245	1.440	4,593		Araldite GY 250	25068-38-6	2.00	
Aluminium-hydroxide-oxide	24623-77-6	Lead Frame	0.153	0.480	1,531	(2-Met	hoxymethylethoxy)propanol	34590-94-8	0.80	
Gold	7440-57-5	Lead Frame	0.031	0.096	306	`	Bisphenol A	80-05-7	1.50	
Silicon	7440-21-3	Die Attach	0.525	1.646	5,250		Aluminium-hydroxide-oxide	24623-77-6	0.50	
Silver	7440-22-4	Die Attach	0.180	0.564	1,800		Gold	7440-57-5	0.10	
Epoxy Resin	Trade secret	Die Attach	0.045	0.141	450			Total	100.00	
Silicon	7440-21-3	Chip (Die)	5.190	16.271	51,900	2.35	(mg) Total	Die Attach	% of Total Weight	0.75
Copper (Cu)	7440-50-8	Wire Bond	0.175	0.549	1,751		Silicon	7440-21-3	70.00	
Palladium	7440-05-3	Wire Bond	0.005	0.015	49		Silver	7440-22-4	24.00	
Tin	7440-31-5	Plating on external leads (pins)	6.967	21.842	69,673 2.166		Epoxy Resin	Trade secret	6.00	
Silver	7440-22-4	Plating on external leads (pins)	0.217	0.679				Total	100.00	
Copper	7440-50-8	Plating on external leads (pins)	0.036	0.113	361	16.27	(mg) Total	Chip (Die)	% of Total Weight	5.19
Copper	•	Plating on external leads (pins) TOTALS:	0.036			16.27	(mg) Total Doped Silicon	Chip (Die) 7440-21-3	% of Total Weight 100.00	5.19
	0.3135 g T	Plating on external leads (pins) TOTALS: otal Mass	0.036 100.000	0.113 313.500	361 1,000,000		Doped Silicon	Chip (Die) 7440-21-3 Total	% of Total Weight 100.00 100.00	
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